

CL49-8241

Conductor

Description

CL49-8241 is a mixed bonded Ag/Pd/Pt conductor material. It offers cost savings over standard Ag/Pd/Pt formulations while maintaining the advantages of leach resistance and aged adhesion. CL49-8241 is supplied with a rheology, which results in a dense, uniform fired film.

Key Features

- Low cost Excellent solderability and leach resistance
- Low resistivity Excellent aged adhesion



This picture does not show the packaging of CL49-8241 and is solely intended for illustration purposes. The products are available in different packaging configurations and may change over time. Please refer to the latest safety data sheets for safety-relevant pictograms.

Typical Properties

Conductivity	≤ 5.0 milliohms per square at 12 microns fired film thickness
Viscosity	100 – 170 kcps Brookfield HBT SC4 – 14 spindle and 6R cup at 10 rpm, 25 °C
Solids	79.8 ± 1.00 %
Coverage	85 cm ² /g at 12 microns fired film thickness
Metal	AgPdPt

Recommended Processing Guide

Printing Parameters	280 – 325 stainless mesh screen 0.5 mil emulsion 1.1 mil wire
Drying Temperature	150 °C for 5 to 10 minutes
Process Temperature (TDS)	850 °C peak temperature Dwell time of 9 – 11 minutes
Film Thickness	Dried: 20 – 25 µm Fired: 10 – 15 µm
Recommended Thinner	RV-507

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Warranty

3 months

Storage

Store in a dry location at 5 – 25 °

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